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**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE

**EXCESS CLAIM FEE PAYMENT LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

An Amendment Under 37 C.F.R. § 1.111 is attached hereto for concurrent filing in the  
above-identified application. The resulting excess claim fee has been calculated as shown  
below:

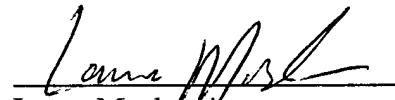
	After Amendment	Highest No. Previously Paid For	
All Claims	<u>25</u>	<u>24</u> = <u>1</u> X <u>\$50.00</u> = <u>\$50.00</u>	
Independent	<u>2</u>	<u>3</u> = <u>1</u> X <u>\$200.00</u> = <u>\$.00</u>	
		<b>TOTAL</b>	<b>= \$50.00</b>

**EXCESS CLAIM FEE PAYMENT LETTER**  
U.S. Application No. 10/721,384

**Q73159**

A check for the statutory fee of \$50.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this letter is enclosed.

Respectfully submitted,



Laura Moskowitz  
Registration No. 55,470

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WASHINGTON OFFICE  
**23373**  
CUSTOMER NUMBER

Date: January 28, 2005